PART INFORMATION	
Mfg Item Number	MCIMX357DJQ5C
Mfg Item Name	MAPBGA 400 17*17*0.8P0.8

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2014-11-24
Response Document ID	5284K10745D080A1.12
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

MANUFACTURING	
Mfg Item Number	MCIMX357DJQ5C
Mfg Item Name	MAPBGA 400 17*17*0.8P0.8
Version	ALL
Weight	0.838700
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
	6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c) : Copper alloy containing up to 4% lead by weight
	7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0043						g					
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00316842	g	736842	73.6842		3777	0.3777
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Di-ester resin	-		0.00045263	g	105263	10.5263		539	0.0539
Epoxy Die Attach		Solvents, additives, and other materials	Proprietary Material-Functionalized Ester	-		0.00045263	g	105263	10.5263		539	0.0539
Epoxy Die Attach		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.00022632	g	52632	5.2632		269	0.0269
Silicon Semiconductor Die	0.0335						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00067	g	20000	2		798	0.0798
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.03283	g	980000	98		39143	3.9143
Organic Substrate, Halogen-fre	0.294						g					
Organic Substrate, Halogen-fre		Pigments and Dyes	Proprietary Material-Other azo dyes	-		0.00009555	g	325	0.0325		113	0.0113
Organic Substrate, Halogen-fre		Metals	Barium sulfate	7727-43-7		0.01231566	g	41890	4.189		14684	1.4684
Organic Substrate, Halogen-fre		Metals	Copper, metal	7440-50-8		0.15976784	g	543428	54.3428		190494	19.0494
Organic Substrate, Halogen-fre		Metals	Gold, metal	7440-57-5		0.00298351	g	10148	1.0148		3557	0.3557
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Other inorganic compounds.	-		0.02955317	g	100521	10.0521		35236	3.5236
Organic Substrate, Halogen-fre		Nickel (external applications only)	Nickel	7440-02-0		0.00895024	g	30443	3.0443		10671	1.0671
Organic Substrate, Halogen-fre		Glass	Proprietary Material-Other glass compounds (without lead, chromium, cadmium or mercury)	-		0.0228829	g	77833	7.7833		27283	2.7283
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00190953	g	6495	0.6495		2276	0.2276
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Proprietary Material-Other Aromatic carbonyl compounds	-		0.00119335	g	4059	0.4059		1422	0.1422
Organic Substrate, Halogen-fre		Plastics/polymers	Other acrylic resins	-		0.00186161	g	6332	0.6332		2219	0.2219
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Proprietary Material-Other aliphatic amine compounds	-		0.0001911	g	650	0.065		227	0.0227
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	3-methoxy-3-methyl-1-butyl acetate	103429-90-9		0.00677846	g	23056	2.3056		8082	0.8082
Organic Substrate, Halogen-fre		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.04551708	g	154820	15.482		54270	5.427
Solder Balls - Lead Free	0.1034						g					
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.00051824	g	5012	0.5012		617	0.0617
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.00103648	g	10024	1.0024		1235	0.1235
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.10184528	g	984964	98.4964		121432	12.1432
Bonding Wire, Copper	0.0051						g					
Bonding Wire, Copper		Metals	Copper, metal	7440-50-8		0.004947	g	970000	97		5898	0.5898
Bonding Wire, Copper		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000153	g	30000	3		182	0.0182
Die Encapsulant, Halogen-free	0.3984						g					
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00125337	g	3146	0.3146		1494	0.1494
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.01880209	g	47194	4.7194		22418	2.2418
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.35536363	g	891977	89.1977		423725	42.3725
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.02298091	g	57683	5.7683		27400	2.74

LINKS	
MCD LINK	
Freescale website	http://www.freescale.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf
China RoHS	http://www.freescale.com/chinarohs
REACH signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf
ELV signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf
Conflict Minerals statement	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf
FREESCALE ENVIRONMENTAL INFORMATION	
EPP website	http://www.freescale.com/epp
FAQ	http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ
Technical Service Request	https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MCIMX357DJQ5C_IPC1752_v11.xml

http://www.freescale.com/mcds/MCIMX357DJQ5C_IPC1752A.xml